

# 具有 8kV HBM ESD 的 TCA9406 2 位双向 1MHz I<sup>2</sup>C 总线和 SMBus 电压电平转换器

## 1 特性

- 适用于 I<sup>2</sup>C 应用中的 SDA 和 SCL 线路的 2 位双向转换器
- 用无方向引脚提供双向电压转换
- 高阻抗输出 SCL\_A、SDA\_A、SCL\_B、SDA\_B 引脚（当 OE = 低电平或 V<sub>CC</sub> = 0V 时）
- 所有 SDA 和 SCL 引脚上都配有内部 10kΩ 上拉电阻器
- A 端口上 1.65V 至 3.6V，B 端口上 2.3V 至 5.5V (V<sub>CCA</sub> ≤ V<sub>CCB</sub>)
- V<sub>CC</sub> 隔离特性：如果任何一个 V<sub>CC</sub> 输入接地 (GND)，则两个端口均处于高阻抗状态
- 无需电源定序：V<sub>CCA</sub> 或 V<sub>CCB</sub> 均可优先斜升
- 当 V<sub>CCA</sub> 或 V<sub>CCB</sub> = 0V 时，可实现低至 2μA 的 I<sub>off</sub>
- OE 输入可直接连接至 V<sub>CCA</sub>，也可通过 GPIO 进行控制
- 闩锁性能超出 JESD 78 II 类规范要求的 100mA
- 静电放电 (ESD) 保护性能超过 JESD 22 规范的要求
  - A 端口
    - 2500V 人体放电模型 (A114-B)
    - 250V 机器放电模式 (A115-A)
    - 1500V 充电器件模型 (C101)
  - B 端口
    - 8kV 人体放电模型 (A114-B)
    - 250V 机器放电模式 (A115-A)
    - 1500V 充电器件模型 (C101)

## 2 应用

- I<sup>2</sup>C/SMBus
- UART
- 通用输入/输出 (GPIO)

## 3 说明

TCA9406 是一款具有输出使能 (OE) 输入的 2 位双向 I<sup>2</sup>C 和 SMBus 电压电平转换器。它在 A 侧的运行电压范围为 1.65V 至 3.6V，基准为 V<sub>CCA</sub>，在 B 侧的运行电压范围为 2.3V 至 5.5V，基准为 V<sub>CCB</sub>。因此，该器件能够在典型的 1.8V、2.5V、3.3V 和 5V 电源轨之间，进行任何高低逻辑信号电平切换。

OE 输入引脚的基准为 V<sub>CCA</sub>，可以直接连接至 V<sub>CCA</sub>，但也可以承受 5.5V 的电压。用户还可以对 OE 引脚进行控制，将其设置为低电平，使所有 SCL 和 SDA 引脚均处于高阻抗状态，从而显著减少静态电流消耗。

在正常 I<sup>2</sup>C 和 SMBus 运行配置或其他漏极开路配置下，TCA9406 可以支持最高 2Mbps 的速度，因此，它可以达到标准 I<sup>2</sup>C 速度要求，即 SCL 频率为 100kHz（标准模式）、400kHz（快速模式）或 1MHz（快速模式升级版）。该器件还可用作通用电平转换器，而且当 A 侧和 B 侧端口均是通过推挽式器件驱动时，TCA9406 可支持最高 24Mbps 的速度。

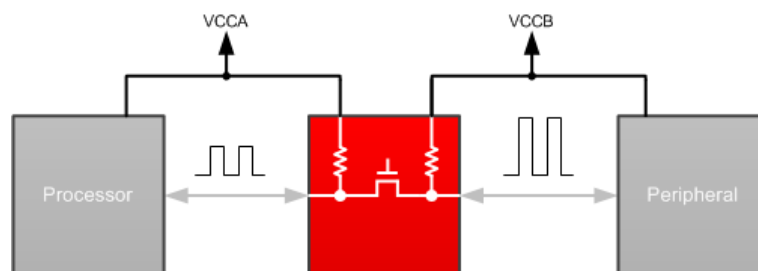
TCA9406 在 SCL\_A、SDA\_A、SCL\_B 和 SDA\_B 上具有内部 10kΩ 上拉电阻器。您还可以向总线添加额外的上拉电阻器，从而减小总上拉电阻并加快上升沿的上升速度。

器件信息<sup>(1)</sup>

器件型号	封装	封装尺寸 (标称值)
TCA9406	SM8 (8)	2.95mm × 2.80mm
	US8 (8)	2.30mm × 2.00mm
	DSBGA (8)	1.90mm × 0.90mm

(1) 如需了解所有可用封装，请见数据表末尾的可订购产品附录。

TCA9406 典型应用方框图



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## 4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

Changes from Revision F (October 2018) to Revision G	Page
• Changed section title From: Pullup or Pulldown Resistors on I/O Lines To: Pullup Resistors on I/O Lines .....	20
• Deleted text "An external pull down..." and Equation 1 from the <i>Detailed Design Procedure</i> section .....	21
• Changed pin 1 From: To controller To: To system in 图 13 .....	23
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Changes from Revision E (August 2018) to Revision F	Page
• Changed the <i>Functional Block Diagram</i> .....	18
• Changed the <i>Enable and Disable</i> section .....	19

Changes from Revision D (July 2018) to Revision E	Page
• Changed the new DSBGA pinout drawing From: Bottom View to: Top View .....	5

Changes from Revision C (December 2014) to Revision D	Page
• Changed the updated pinout drawings .....	5
• Changed $t_{dis}$ no external load MAX values From: 50 To: 200 ns in <i>Switching Characteristics</i> ( $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ ) .....	10
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- Changed  $t_{dis}$  no external load MAX values From: 35 To: 200 ns in *Switching Characteristics* ( $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$ )..... 14
  - Changed the *Parameter Measurement Information* section..... 16
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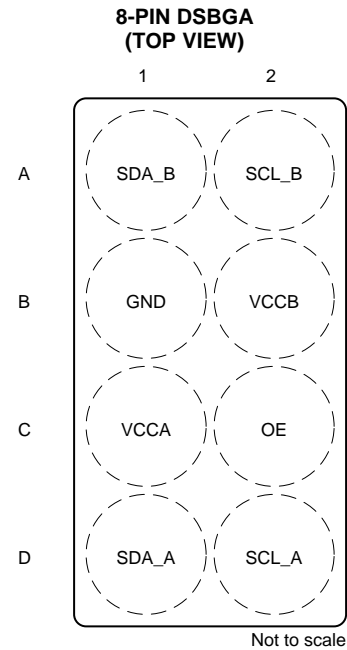
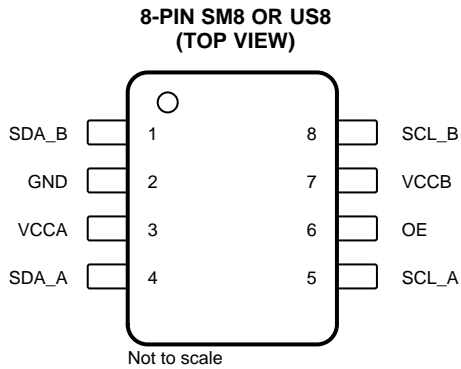
**Changes from Revision B (June 2013) to Revision C**
**Page**

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- 已添加 引脚配置和功能 部分、*ESD* 额定值 表、特性 说明 部分、器件功能模式、应用和实施 部分、电源相关建议 部分、布局 部分、器件和文档支持 部分以及机械、封装和可订购信息 部分 ..... [1](#)
- 

**Changes from Revision A (February 2013) to Revision B**
**Page**

- 
- 删除了订购信息表，您现在可以在 POA 中找到相应的信息 ..... [1](#)
-

## 5 Pin Configuration and Functions



### Pin Functions

PIN			TYPE	DESCRIPTION
NAME	DCT, DCU	YZP		
SDA_B	1	A1	I/O	Input/output B. Referenced to $V_{CCB}$ .
GND	2	B1	GND	Ground
VCCA	3	C1	Power	A-port supply voltage. $1.65\text{ V} \leq V_{CCA} \leq 3.6\text{ V}$ and $V_{CCA} \leq V_{CCB}$
SDA_A	4	D1	I/O	Input/output A. Referenced to $V_{CCA}$ .
SCL_A	5	D2	I/O	Input/output A. Referenced to $V_{CCA}$ .
OE	6	C2	Input	Output enable (active High). Pull OE low to place all outputs in 3-state mode. Referenced to $V_{CCA}$ .
VCCB	7	B2	Power	B-port supply voltage. $2.3\text{ V} \leq V_{CCB} \leq 5.5\text{ V}$
SCL_B	8	A2	I/O	Input/output B. Referenced to $V_{CCB}$ .

## 6 Specifications

### 6.1 Absolute Maximum Ratings<sup>(1)</sup>

over recommended operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CCA}$	Supply voltage range		−0.5	4.6	V
$V_{CCB}$	Supply voltage range		−0.5	6.5	V
$V_I$	Input voltage range <sup>(2)</sup>	A port	−0.5	4.6	V
		B port	−0.5	6.5	
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	A port	−0.5	4.6	V
		B port	−0.5	6.5	
$V_O$	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	A port	−0.5	$V_{CCA} + 0.5$	V
		B port	−0.5	$V_{CCB} + 0.5$	
$I_{IK}$	Input clamp current	$V_I < 0$		−50	mA
$I_{OK}$	Output clamp current	$V_O < 0$		−50	mA
$I_O$	Continuous output current			±50	mA
	Continuous current through $V_{CCA}$ , $V_{CCB}$ , or GND			±100	mA
$T_{stg}$	Storage temperature		−65	150	°C

- (1) Stresses beyond those listed under [Absolute Maximum Ratings](#) may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under [Recommended Operating Conditions](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of  $V_{CCA}$  and  $V_{CCB}$  are provided in the recommended operating conditions table.

### 6.2 ESD Ratings

			VALUE	UNIT	
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	A-Port	±2500	V
			B-Port	±8000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>		±1500	V
		Machine model (MM), A115-A		±250	V

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

$V_{CCI}$  is the supply voltage associated with the input port.  $V_{CCO}$  is the supply voltage associated with the output port.

			V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	MAX	UNIT
V <sub>CCA</sub>	Supply voltage <sup>(1)</sup>				1.65	3.6	V
V <sub>CCB</sub>	Supply voltage				2.3	5.5	V
V <sub>IH</sub>	High-level input voltage	A-port I/Os	1.65 V to 1.95 V	2.3 V to 5.5 V	V <sub>CCI</sub> − 0.2	V <sub>CCI</sub>	V
			2.3 V to 3.6 V		V <sub>CCI</sub> − 0.4	V <sub>CCI</sub>	
		B-port I/Os	1.65 V to 3.6 V	2.3 V to 5.5 V	V <sub>CCI</sub> − 0.4	V <sub>CCI</sub>	
					OE input	V <sub>CCA</sub> × 0.65	
V <sub>IL</sub> <sup>(2)</sup>	Low-level input voltage	A-port I/Os	1.65 V to 3.6 V	2.3 V to 5.5 V	0	0.15	V
		B-port I/Os			0	0.15	
		OE input			0	V <sub>CCA</sub> × 0.35	
ΔT/Δv	Input transition rise or fall rate	A-port I/Os, push-pull driving	1.65 V to 3.6 V	2.3 V to 5.5 V	10		ns/V
		B-port I/Os, push-pull driving			10		
		Control input			10		
T <sub>A</sub>	Operating free-air temperature				−40	85	°C

(1)  $V_{CCA}$  must be less than or equal to  $V_{CCB}$  (except during power-on transient time), and  $V_{CCA}$  must not exceed 3.6 V.

(2) The maximum  $V_{IL}$  value is provided to ensure that a valid  $V_{OL}$  is maintained. The  $V_{OL}$  value is  $V_{IL}$  plus the voltage drop across the pass-gate transistor.

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TCA9406			UNIT
		DCT	DCU	YZP	
		8 PINS	8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	182.6	199.1	105.8	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	113.3	72.4	1.6	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	94.9	77.8	10.8	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	39.4	6.2	3.1	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	93.9	77.4	10.8	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics<sup>(1)(2)(3)</sup>

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = 25°C	−40°C to 85°C		UNIT
					TYP	MIN	MAX	
V <sub>OHA</sub>		I <sub>OH</sub> = −20 μA, V <sub>IB</sub> ≥ V <sub>CCB</sub> − 0.4 V	1.65 V to 3.6 V	2.3 V to 5.5 V	V <sub>CCA</sub> × 0.67			V
V <sub>OLA</sub>		I <sub>OL</sub> = 1 mA, V <sub>IB</sub> ≤ 0.15 V	1.65 V to 3.6 V	2.3 V to 5.5 V	0.4			V
V <sub>OHB</sub>		I <sub>OH</sub> = −20 μA, V <sub>IA</sub> ≥ V <sub>CCA</sub> − 0.2 V	1.65 V to 3.6 V	2.3 V to 5.5 V	V <sub>CCB</sub> × 0.67			V
V <sub>OLB</sub>		I <sub>OL</sub> = 1 mA, V <sub>IA</sub> ≤ 0.15 V	1.65 V to 3.6 V	2.3 V to 5.5 V	0.4			V
I <sub>I</sub>	OE	V <sub>I</sub> = V <sub>CCI</sub> or GND	1.65 V to 3.6 V	2.3 V to 5.5 V	±1		±2	μA
I <sub>off</sub>	A port		0 V	0 V to 5.5 V	±1		±2	μA
	B port		0 to 3.6 V	0 V	±1		±2	μA
I <sub>OZ</sub>	A or B port	OE less than V <sub>IL</sub>	1.65 V to 3.6 V	2.3 V to 5.5 V	±1		±2	μA
I <sub>CCA</sub>		V <sub>I</sub> = V <sub>O</sub> = open, I <sub>O</sub> = 0	1.65 V to V <sub>CCB</sub>	2.3 V to 5.5 V			2.4	μA
			3.6 V	0 V			2.2	
			0 V	5.5 V			−1	
I <sub>CCB</sub>		V <sub>I</sub> = V <sub>O</sub> = open, I <sub>O</sub> = 0	1.65 V to V <sub>CCB</sub>	2.3 V to 5.5 V			12	μA
			3.6 V	0 V			−1	
			0 V	5.5 V			1	
I <sub>CCA</sub> + I <sub>CCB</sub>		V <sub>I</sub> = V <sub>O</sub> = open, I <sub>O</sub> = 0	1.65 V to V <sub>CCB</sub>	2.3 V to 5.5 V			14.4	μA
C <sub>I</sub>	OE		3.3 V	3.3 V	2.5		3.5	pF
C <sub>io</sub>	A or B port		3.3 V	3.3 V	10			pF
	A port				5	6		
	B port				6	7.5		

(1)  $V_{CCI}$  is the  $V_{CC}$  associated with the input port.

(2)  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.

(3)  $V_{CCA}$  must be less than or equal to  $V_{CCB}$ , and  $V_{CCA}$  must not exceed 3.6 V.



## 6.6 Timing Requirements ( $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ )

over recommended operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
V <sub>CCB</sub> = 2.5 V ± 0.2 V						
Data rate	Push-pull driving			21		Mbps
	Open-drain driving			2		
t <sub>w</sub> Pulse duration	Push-pull driving		Data inputs	47		ns
	Open-drain driving			500		
V <sub>CC</sub> = 3.3 V ± 0.3 V						
Data rate	Push-pull driving			22		Mbps
	Open-drain driving			2		
t <sub>w</sub> Pulse duration	Push-pull driving		Data inputs	45		ns
	Open-drain driving			500		
V <sub>CC</sub> = 5 V ± 0.5 V						
Data rate	Push-pull driving			24		Mbps
	Open-drain driving			2		
t <sub>w</sub> Pulse duration	Push-pull driving		Data inputs	41		ns
	Open-drain driving			500		

## 6.7 Timing Requirements ( $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ )

over recommended operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
V <sub>CCB</sub> = 2.5 V ± 0.2 V						
Data rate	Push-pull driving			20		Mbps
	Open-drain driving			2		
t <sub>w</sub> Pulse duration	Push-pull driving		Data inputs	50		ns
	Open-drain driving			500		
V <sub>CC</sub> = 3.3 V ± 0.3 V						
Data rate	Push-pull driving			22		Mbps
	Open-drain driving			2		
t <sub>w</sub> Pulse duration	Push-pull driving		Data inputs	45		ns
	Open-drain driving			500		
V <sub>CC</sub> = 5 V ± 0.5 V						
Data rate	Push-pull driving			24		Mbps
	Open-drain driving			2		
t <sub>w</sub> Pulse duration	Push-pull driving		Data inputs	41		ns
	Open-drain driving			500		

## 6.8 Timing Requirements ( $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$ )

over recommended operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
V <sub>CC</sub> = 3.3 V ± 0.3 V						
Data rate	Push-pull driving			23		Mbps
	Open-drain driving			2		
t <sub>w</sub> Pulse duration	Push-pull driving		Data inputs	43		ns
	Open-drain driving			500		
V <sub>CC</sub> = 5 V ± 0.5 V						
Data rate	Push-pull driving			24		Mbps
	Open-drain driving			2		
t <sub>w</sub> Pulse duration	Push-pull driving		Data inputs	41		ns
	Open-drain driving			500		

## 6.9 Switching Characteristics ( $V_{CCA} = 1.8 \text{ V} \pm 0.15 \text{ V}$ )

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
V <sub>CCB</sub> = 2.5 V ± 0.2 V						
t <sub>PHL</sub>	A	B	Push-pull driving		5.3	ns
t <sub>PLH</sub>			Open-drain driving	2.3	8.8	
			Push-pull driving		6.8	
			Open-drain driving		50	
t <sub>PHL</sub>	B	A	Push-pull driving		4.4	ns
t <sub>PLH</sub>			Open-drain driving	1.9	5.3	
			Push-pull driving		5.3	
			Open-drain driving		5.3	
t <sub>en</sub>	OE	A or B			200	ns
t <sub>dis</sub>	OE	A or B	with external load		200	ns
			no external load		200	ns
t <sub>rA</sub>	A-port rise time		Push-pull driving		9.5	ns
			Open-drain driving	38	165	
t <sub>rB</sub>	B-port rise time		Push-pull driving		10.8	ns
			Open-drain driving	34	145	
t <sub>fA</sub>	A-port fall time		Push-pull driving		5.9	ns
			Open-drain driving		6.9	
t <sub>fB</sub>	B-port fall time		Push-pull driving		13.8	
			Open-drain driving		13.8	
t <sub>SK(O)</sub>	Channel-to-channel skew				0.7	ns
Max data rate			Push-pull driving	21		Mbps
			Open-drain driving	2		
V <sub>CCB</sub> = 3.3 V ± 0.3 V						
t <sub>PHL</sub>	A	B	Push-pull driving		5.4	ns
t <sub>PLH</sub>			Open-drain driving	2.4	9.6	
			Push-pull driving		7.1	
			Open-drain driving		40	
t <sub>PHL</sub>	B	A	Push-pull driving		4.5	ns
t <sub>PLH</sub>			Open-drain driving	1.1	4.4	
			Push-pull driving		4.5	
			Open-drain driving		4.5	
t <sub>en</sub>	OE	A or B			200	ns
t <sub>dis</sub>	OE	A or B	with external load		200	ns
			no external load		200	ns
t <sub>rA</sub>	A-port rise time		Push-pull driving		9.3	ns
			Open-drain driving	30	132	
t <sub>rB</sub>	B-port rise time		Push-pull driving		9.1	ns
			Open-drain driving	23	106	
t <sub>fA</sub>	A-port fall time		Push-pull driving		6	ns
			Open-drain driving		6.4	
t <sub>fB</sub>	B-port fall time		Push-pull driving		16.2	ns
			Open-drain driving		16.2	
t <sub>SK(O)</sub>	Channel-to-channel skew				0.7	ns
Max data rate			Push-pull driving	22		Mbps
			Open-drain driving	2		

**Switching Characteristics ( $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$ ) (continued)**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
V <sub>CCB</sub> = 5 V ± 0.5 V						
t <sub>PHL</sub>	A	B	Push-pull driving		6.8	ns
t <sub>PLH</sub>			Open-drain driving	2.6	10	
			Push-pull driving		7.5	
			Open-drain driving		33	
t <sub>PHL</sub>	B	A	Push-pull driving		4.7	ns
t <sub>PLH</sub>			Open-drain driving	1.2	4	
			Push-pull driving		0.5	
			Open-drain driving		0.5	
t <sub>en</sub>	OE	A or B			200	ns
t <sub>dis</sub>	OE	A or B	with external load		200	ns
			no external load		200	ns
t <sub>rA</sub>	A-port rise time		Push-pull driving		7.6	ns
			Open-drain driving	22	95	
t <sub>rB</sub>	B-port rise time		Push-pull driving		7.6	ns
			Open-drain driving	10	58	
t <sub>fA</sub>	A-port fall time		Push-pull driving		13.3	ns
			Open-drain driving		6.1	
t <sub>fB</sub>	B-port fall time		Push-pull driving		16.2	ns
			Open-drain driving		16.2	
t <sub>SK(O)</sub>	Channel-to-channel skew				0.7	ns
Max data rate			Push-pull driving	24		Mbps
			Open-drain driving	2		

## 6.10 Switching Characteristics ( $V_{CCA} = 2.5 \text{ V} \pm 0.2 \text{ V}$ )

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
V <sub>CCB</sub> = 2.5 V ± 0.2 V						
t <sub>PHL</sub>	A	B	Push-pull driving		3.2	ns
t <sub>PLH</sub>			Open-drain driving	1.7	6.3	
			Push-pull driving		3.5	
			Open-drain driving		3.5	
t <sub>PHL</sub>	B	A	Push-pull driving		3	ns
t <sub>PLH</sub>			Open-drain driving	1.8	4.7	
			Push-pull driving		2.5	
			Open-drain driving		2.5	
t <sub>en</sub>	OE	A or B			200	ns
t <sub>dis</sub>	OE	A or B	with external load		200	ns
			no external load		200	ns
t <sub>rA</sub>	A-port rise time		Push-pull driving		7.4	ns
			Open-drain driving	34	149	
t <sub>rB</sub>	B-port rise time		Push-pull driving		8.3	ns
			Open-drain driving	35	151	
t <sub>fA</sub>	A-port fall time		Push-pull driving		5.7	ns
			Open-drain driving		6.9	
t <sub>fB</sub>	B-port fall time		Push-pull driving		7.8	
			Open-drain driving		8.8	
t <sub>SK(O)</sub>	Channel-to-channel skew				0.7	ns
Max data rate			Push-pull driving	20		Mbps
			Open-drain driving	2		
V <sub>CCB</sub> = 3.3 V ± 0.3 V						
t <sub>PHL</sub>	A	B	Push-pull driving		3.7	ns
t <sub>PLH</sub>			Open-drain driving	2	6	
			Push-pull driving		4.1	
			Open-drain driving		4.1	
t <sub>PHL</sub>	B	A	Push-pull driving		3.6	ns
t <sub>PLH</sub>			Open-drain driving	2.6	4.2	
			Push-pull driving		1.6	
			Open-drain driving		1.6	
t <sub>en</sub>	OE	A or B			200	ns
t <sub>dis</sub>	OE	A or B	with external load		200	ns
			no external load		200	ns
t <sub>rA</sub>	A-port rise time		Push-pull driving		6.6	ns
			Open-drain driving	28	121	
t <sub>rB</sub>	B-port rise time		Push-pull driving		7.2	ns
			Open-drain driving	24	112	
t <sub>fA</sub>	A-port fall time		Push-pull driving		5.5	ns
			Open-drain driving		6.2	
t <sub>fB</sub>	B-port fall time		Push-pull driving		6.7	ns
			Open-drain driving		9.4	
t <sub>SK(O)</sub>	Channel-to-channel skew				0.7	ns
Max data rate			Push-pull driving	22		Mbps
			Open-drain driving	2		

**Switching Characteristics ( $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$ ) (continued)**

over recommended operating free-air temperature range (unless otherwise noted)

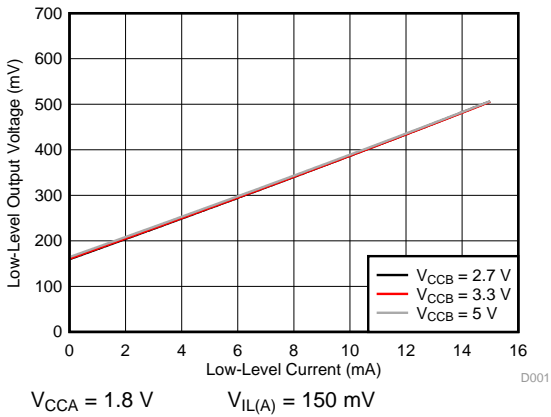
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
V <sub>CCB</sub> = 5 V ± 0.5 V						
t <sub>PHL</sub>	A	B	Push-pull driving		3.8	ns
t <sub>PLH</sub>			Open-drain driving	2.1	5.8	
			Push-pull driving		4.4	
			Open-drain driving		4.4	
t <sub>PHL</sub>	B	A	Push-pull driving		4.3	ns
t <sub>PLH</sub>			Open-drain driving	1.2	4	
			Push-pull driving		1	
			Open-drain driving		1	
t <sub>en</sub>	OE	A or B			200	ns
t <sub>dis</sub>	OE	A or B	with external load		200	ns
			no external load		200	ns
t <sub>rA</sub>	A-port rise time		Push-pull driving		5.6	ns
			Open-drain driving	24	89	
t <sub>rB</sub>	B-port rise time		Push-pull driving		6.1	ns
			Open-drain driving	12	64	
t <sub>fA</sub>	A-port fall time		Push-pull driving		5.3	ns
			Open-drain driving		5.8	
t <sub>fB</sub>	B-port fall time		Push-pull driving		6.6	ns
			Open-drain driving		10.4	
t <sub>SK(O)</sub>	Channel-to-channel skew				0.7	ns
Max data rate			Push-pull driving	24		Mbps
			Open-drain driving	2		

## 6.11 Switching Characteristics ( $V_{CCA} = 3.3 \text{ V} \pm 0.3 \text{ V}$ )

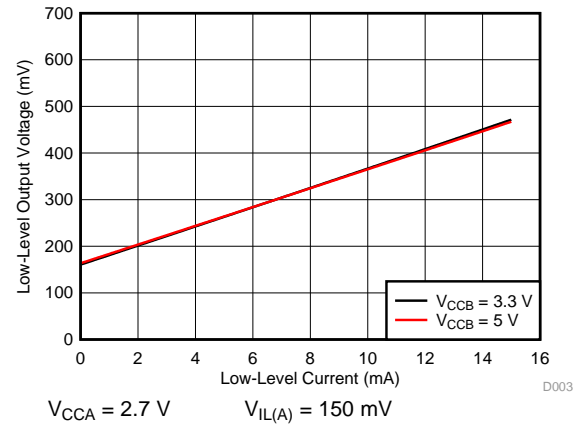
over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT
V <sub>CCB</sub> = 3.3 V ± 0.3 V						
t <sub>PHL</sub>	A	B	Push-pull driving		2.4	ns
t <sub>PLH</sub>			Open-drain driving	1.3	4.2	
			Push-pull driving		4.2	
			Open-drain driving		4.2	
t <sub>PHL</sub>	B	A	Push-pull driving		2.5	ns
t <sub>PLH</sub>			Open-drain driving	1	124	
			Push-pull driving		2.5	
			Open-drain driving		2.5	
t <sub>en</sub>	OE	A or B			200	ns
t <sub>dis</sub>	OE	A or B	with external load		200	ns
			no external load		200	ns
t <sub>rA</sub>	A-port rise time		Push-pull driving		5.6	ns
			Open-drain driving	25	116	
t <sub>rB</sub>	B-port rise time		Push-pull driving		6.4	ns
			Open-drain driving	26	116	
t <sub>fA</sub>	A-port fall time		Push-pull driving		5.4	ns
			Open-drain driving		6.1	
t <sub>fB</sub>	B-port fall time		Push-pull driving		7.4	ns
			Open-drain driving		7.6	
t <sub>SK(O)</sub>	Channel-to-channel skew				0.7	ns
Max data rate			Push-pull driving	23		Mbps
			Open-drain driving	2		
V <sub>CCB</sub> = 5 V ± 0.5 V						
t <sub>PHL</sub>	A	B	Push-pull driving		3.1	ns
t <sub>PLH</sub>			Open-drain driving	1.4	4.6	
			Push-pull driving		4.4	
			Open-drain driving		4.4	
t <sub>PHL</sub>	B	A	Push-pull driving		3.3	ns
t <sub>PLH</sub>			Open-drain driving	1	97	
			Push-pull driving		2.6	
			Open-drain driving		2.6	
t <sub>en</sub>	OE	A or B			200	ns
t <sub>dis</sub>	OE	A or B	with external load		200	ns
			no external load		200	ns
t <sub>rA</sub>	A-port rise time		Push-pull driving		4.8	ns
			Open-drain driving	19	85	
t <sub>rB</sub>	B-port rise time		Push-pull driving		7.4	ns
			Open-drain driving	14	72	
t <sub>fA</sub>	A-port fall time		Push-pull driving		5	ns
			Open-drain driving		5.7	
t <sub>fB</sub>	B-port fall time		Push-pull driving		7.6	ns
			Open-drain driving		8.3	
t <sub>SK(O)</sub>	Channel-to-channel skew				0.7	ns
Max data rate			Push-pull driving	24		Mbps
			Open-drain driving	2		

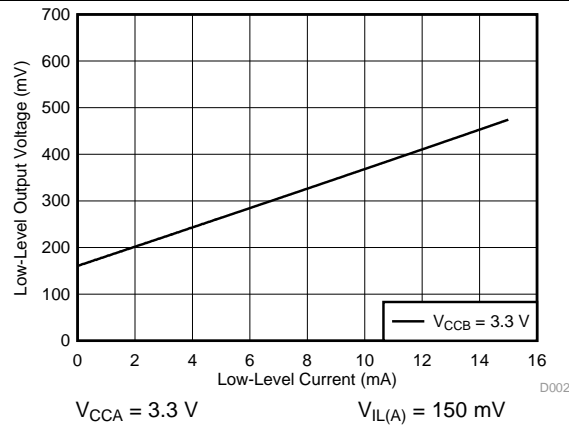
## 6.12 Typical Characteristics



**图 1. Low-Level Output Voltage ( $V_{OL(Bx)}$ ) vs Low-Level Current ( $I_{OL(Bx)}$ )**

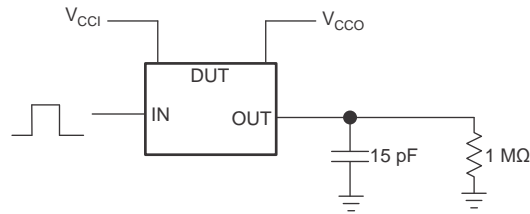


**图 2. Low-Level Output Voltage ( $V_{OL(Bx)}$ ) vs Low-Level Current ( $I_{OL(Bx)}$ )**

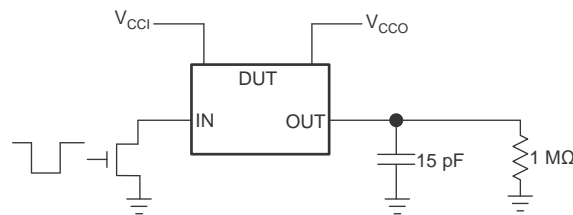


**图 3. Low-Level Output Voltage ( $V_{OL(Bx)}$ ) vs Low-Level Current ( $I_{OL(Bx)}$ )**

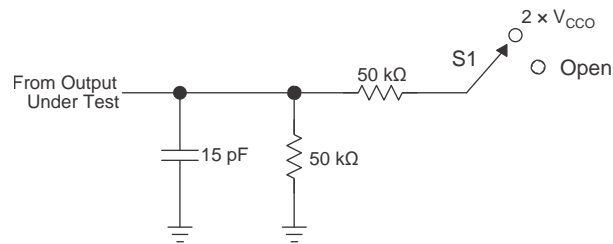
## 7 Parameter Measurement Information



**图 4. Data Rate, Pulse Duration, Propagation Delay, Output Rise-Time and Fall-Time Measurement Using a Push-Pull Driver**



**图 5. Data Rate, Pulse Duration, Propagation Delay, Output Rise-Time and Fall-Time Measurement Using an Open-Drain Driver**



TEST	S1
$t_{PZL} / t_{PLZ}$	$2 \times V_{CCO}$
$t_{PHZ} / t_{PZH}$	Open

**图 6. Load Circuit for Enable-Time and Disable-Time Measurement**

1.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
2.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
3.  $V_{CCI}$  is the  $V_{CC}$  associated with the input port.
4.  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.



## Parameter Measurement Information (接下页)

### 7.1 Voltage Waveforms

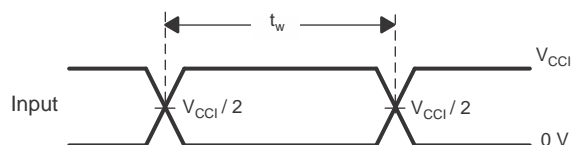


图 7. Pulse Duration

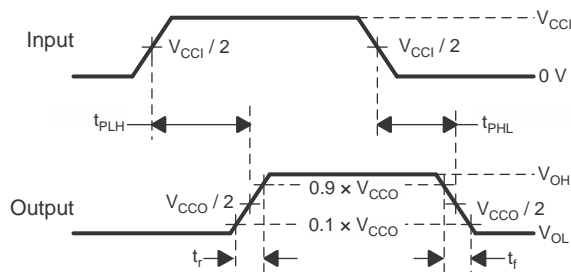


图 8. Propagation Delay Times

- A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 in 图 9 is for an output with internal such that the output is high, except when OE is high (see 图 6). Waveform 2 in 图 9 is for an output with conditions such that the output is low, except when OE is high.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $dv/dt \geq 1 \text{ V/ns}$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H.  $V_{CCI}$  is the  $V_{CC}$  associated with the input port.
- I.  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.

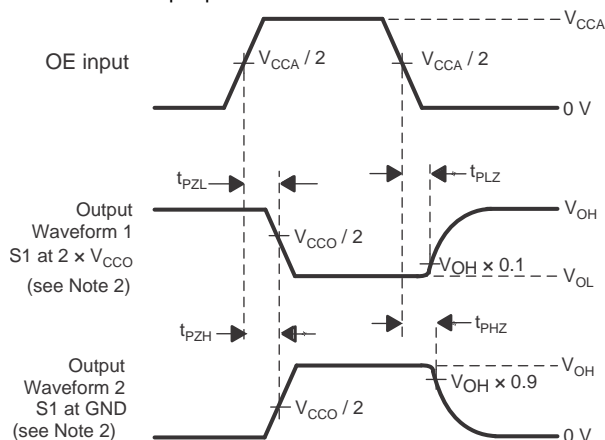


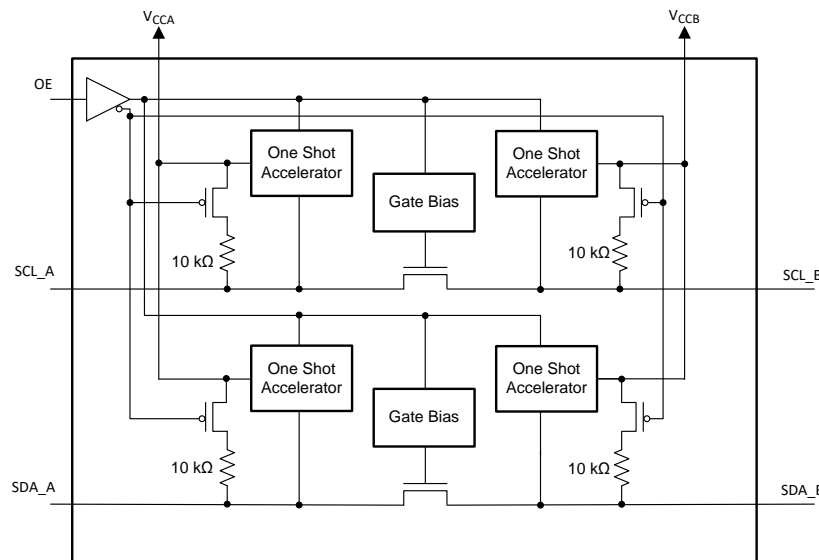
图 9. Enable and Disable Times

## 8 Detailed Description

### 8.1 Overview

The TCA9406 device is a directionless voltage-level translator specifically designed for translating logic voltage levels. The A port is able to accept I/O voltages ranging from 1.65 V to 3.6 V, while the B port can accept I/O voltages from 2.3 V to 5.5 V. The device is a pass-gate architecture with edge-rate accelerators (one-shots) to improve the overall data rate. 10-k $\Omega$  pullup resistors, commonly used in open-drain applications, have been conveniently integrated so that an external resistor is not needed. When TCA9406 is disabled the internal pull up resistors are also disabled. While this device is designed for open-drain applications which makes it ideal for I<sup>2</sup>C and SMBus applications, the device can also translate push-pull CMOS logic outputs.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

#### 8.3.1 Architecture

The TCA9406 architecture (see [Figure 5](#)) is an auto-direction-sensing based translator that does not require a direction-control signal to control the direction of data flow from A to B or from B to A.

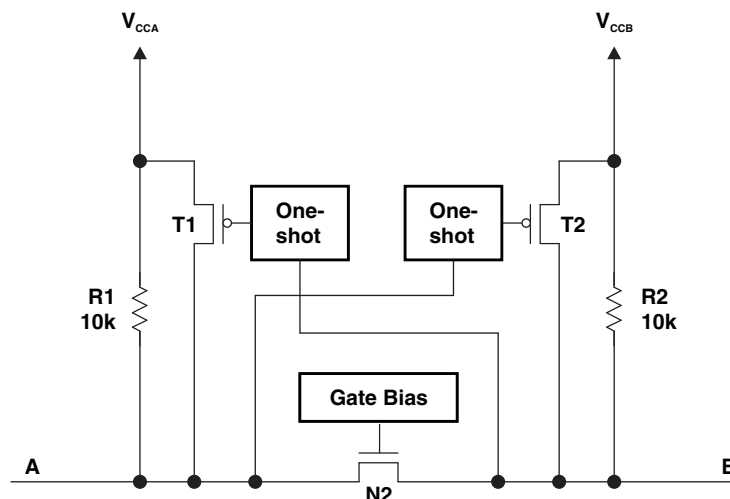


图 10. Architecture of a TCA9406 Cell

## Feature Description (接下页)

These two bidirectional channels independently determine the direction of data flow without a direction-control signal. Each I/O pin is automatically reconfigured as either an input or an output, which is how this auto-direction feature is realized.

The TCA9406 is part of TI's "Switch" type voltage translator family and employs two key circuits to enable this voltage translation:

- 1) An N-channel pass-gate transistor topology that ties the A-port to the B-port  
and
- 2) Output one-shot (O.S.) edge-rate accelerator circuitry to detect and accelerate rising edges on the A or B ports

For bidirectional voltage translation, pullup resistors are included on the device for dc current sourcing capability. The  $V_{GATE}$  gate bias of the N-channel pass transistor is set at approximately one threshold voltage ( $V_T$ ) above the  $V_{CC}$  level of the low-voltage side. Data can flow in either direction without guidance from a control signal.

The O.S. rising-edge rate accelerator circuitry speeds up the output slew rate by monitoring the input edge for transitions, helping maintain the data rate through the device. During a low-to-high signal rising edge, the O.S. circuits turn on the PMOS transistors (T1, T2) to increase the current drive capability of the driver for approximately 30 ns or 95% of the input edge, whichever occurs first. This edge-rate acceleration provides high ac drive by bypassing the internal 10-k $\Omega$  pullup resistors during the low-to-high transition to speed up the signal. The output resistance of the driver is decreased to approximately 50  $\Omega$  to 70  $\Omega$  during this acceleration phase. To minimize dynamic  $I_{CC}$  and the possibility of signal contention, the user should wait for the O.S. circuit to turn off before applying a signal in the opposite direction. The worst-case duration is equal to the minimum pulse-width number provided in the [Timing Requirements](#) section of this data sheet.

### 8.3.2 Input Driver Requirements

The continuous dc-current "sinking" capability is determined by the external system-level open-drain (or push-pull) drivers that are interfaced to the TCA9406 I/O pins. Since the high bandwidth of these bidirectional I/O circuits is used to facilitate this fast change from an input to an output and an output to an input, they have a modest dc-current "sourcing" capability of hundreds of micro-Amps, as determined by the internal 10-k $\Omega$  pullup resistors.

The fall time ( $t_{fA}$ ,  $t_{fB}$ ) of a signal depends on the edge-rate and output impedance of the external device driving TCA9406 data I/Os, as well as the capacitive loading on the data lines.

Similarly, the  $t_{PHL}$  and max data rates also depend on the output impedance of the external driver. The values for  $t_{fA}$ ,  $t_{fB}$ ,  $t_{PHL}$ , and maximum data rates in the data sheet assume that the output impedance of the external driver is less than 50  $\Omega$ .

### 8.3.3 Output Load Considerations

TI recommends careful PCB layout practices with short PCB trace lengths to avoid excessive capacitive loading and to ensure that proper O.S. triggering takes place. PCB signal trace-lengths should be kept short enough such that the round trip delay of any reflection is less than the one-shot duration. This improves signal integrity by ensuring that any reflection sees a low impedance at the driver. The O.S. circuits have been designed to stay on for approximately 30 ns. The maximum capacitance of the lumped load that can be driven also depends directly on the one-shot duration. With very heavy capacitive loads, the one-shot can time-out before the signal is driven fully to the positive rail. The O.S. duration has been set to best optimize trade-offs between dynamic  $I_{CC}$ , load driving capability, and maximum bit-rate considerations. Both PCB trace length and connectors add to the capacitance that the TCA9406 output sees, so it is recommended that this lumped-load capacitance be considered to avoid O.S. re-triggering, bus contention, output signal oscillations, or other adverse system-level affects.

### 8.3.4 Enable and Disable

The TCA9406 has an OE input that is used to disable the device by setting OE low, which places all I/Os in the Hi-Z state. When TCA9406 is disabled, the internal pull up resistors are also disabled meaning if no external pull up resistors are present then the SDA/SCL lines will be left floating. The disable time ( $t_{dis}$ ) indicates the delay between the time when OE goes low and when the outputs are disabled (Hi-Z). The enable time ( $t_{en}$ ) indicates the amount of time the user must allow for the one-shot circuitry to become operational after OE is taken high.

## Feature Description (接下页)

### 8.3.5 Pullup Resistors on I/O Lines

Each A-port I/O has an internal 10-k $\Omega$  pullup resistor to  $V_{CCA}$ , and each B-port I/O has an internal 10-k $\Omega$  pullup resistor to  $V_{CCB}$ . If a smaller value of pullup resistor is required, an external resistor must be added from the I/O to  $V_{CCA}$  or  $V_{CCB}$  (in parallel with the internal 10-k $\Omega$  resistors). Adding lower value pullup resistors will effect  $V_{OL}$  levels, however. The internal pullups of the TCA9406 are disabled when the OE pin is low.

### 8.4 Device Functional Modes

The TCA9406 device has two functional modes, enabled and disabled. To disable the device set the OE input low, which places all I/Os in a high impedance state. Setting the OE input high will enable the device.

## 9 Application and Implementation

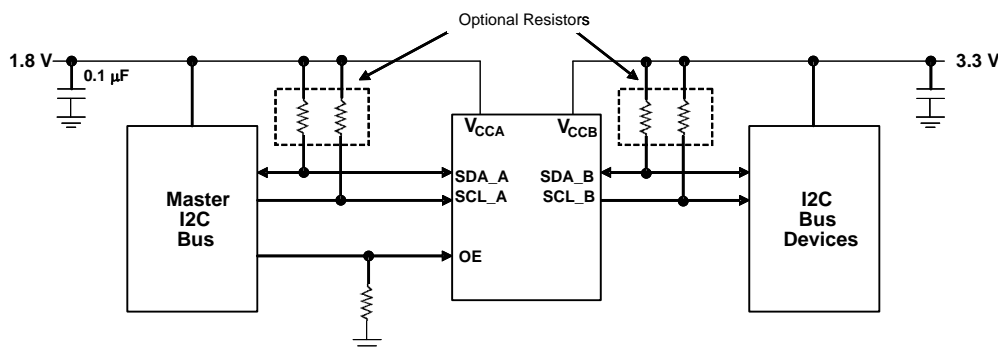
### 注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The TCA9406 can be used to bridge the digital-switching compatibility gap between two voltage nodes to successfully interface logic threshold levels found in electronic systems. It should be used in a point-to-point topology for interfacing devices or systems operating at different interface voltages with one another. Its primary target application use is for interfacing with open-drain drivers on the data I/Os such as I<sup>2</sup>C or SMBus, where the data is bidirectional and no control signal is available.

### 9.2 Typical Application



Design Notes: OE can be tied directly to 1.8 V ( $V_{CCA}$ ) to always be in ENABLE mode.

图 11. Typical Application Circuit

#### 9.2.1 Design Requirements

For this design example, use the parameters listed in Table 1. And make sure the  $V_{CCA} \leq V_{CCB}$ .

表 1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage range	1.65 to 3.6 V
Output voltage range	2.3 to 5.5 V

#### 9.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
  - Use the supply voltage of the device that is driving the TCA9406 device to determine the input voltage range. For a valid logic high the value must exceed the  $V_{IH}$  of the input port. For a valid logic low the value must be less than the  $V_{IL}$  of the input port.
- Output voltage range
  - Use the supply voltage of the device that the TCA9406 device is driving to determine the output voltage range
  - The TCA9406 device has 10-k $\Omega$  internal pullup resistors. External pullup resistors can be added to reduce the total RC of a signal trace if necessary.

## TCA9406

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### 9.2.3 Application Curve

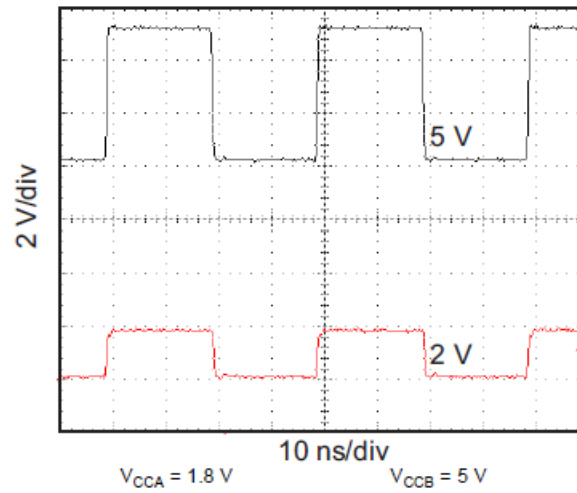


图 12. Level-Translation of a 2.5-MHz Signal

## 10 Power Supply Recommendations

During operation, ensure that  $V_{CCA} \leq V_{CCB}$  at all times. The sequencing of each power supply will not damage the device during the power up operation, so either power supply can be ramped up first. The output-enable (OE) input circuit is designed so that it is supplied by  $V_{CCA}$  and when the (OE) input is low, all outputs are placed in the high-impedance state. To ensure the high-impedance state of the outputs during power up or power down, the OE input pin must be tied to GND through a pulldown resistor and must not be enabled until  $V_{CCA}$  and  $V_{CCB}$  are fully ramped and stable. The minimum value of the pulldown resistor to ground is determined by the current-sourcing capability of the driver.

## 11 Layout

### 11.1 Layout Guidelines

To ensure reliability of the device, the following common printed-circuit board layout guidelines are recommended:

- Bypass capacitors should be used on power supplies and should be placed as close as possible to the  $V_{CCA}$ ,  $V_{CCB}$  pin, and  $G_{ND}$  pin.
- Short trace lengths should be used to avoid excessive loading.
- PCB signal trace-lengths must be kept short enough so that the round-trip delay of any reflection is less than the one-shot duration, approximately 30 ns, ensuring that any reflection encounters low impedance at the source driver.

### 11.2 Layout Example

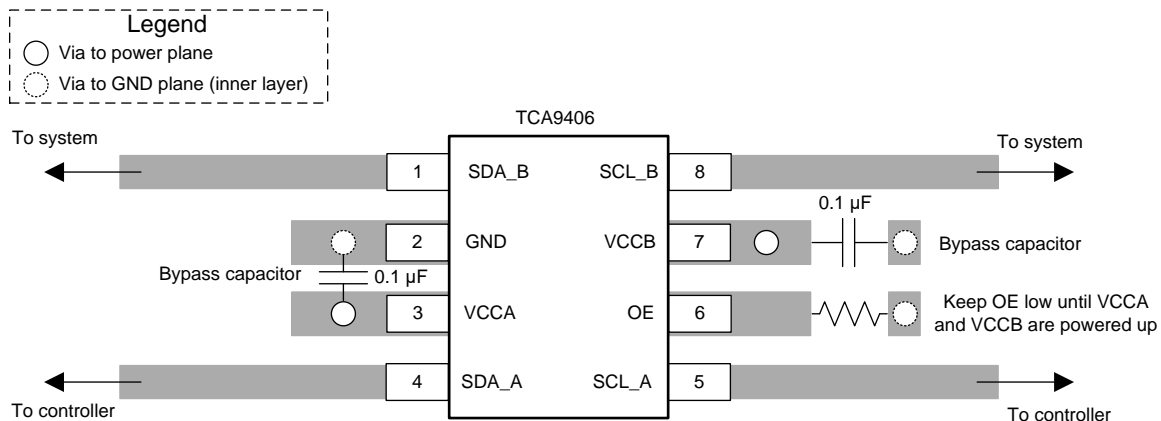


图 13. TCA9406 Layout Example

## 12 器件和文档支持

### 12.1 接收文档更新通知

要接收文档更新通知，请导航至 [TI.com.cn](http://TI.com.cn) 上的器件产品文件夹。单击右上角的通知我进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 12.2 社区资源

下列链接提供到 TI 社区资源的连接。链接的内容由各个分销商“按照原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

**TI E2E™ 在线社区** TI 的工程师对工程师 (E2E) 社区。此社区的创建目的在于促进工程师之间的协作。在 [e2e.ti.com](http://e2e.ti.com) 中，您可以咨询问题、分享知识、拓展思路并与同行工程师一道帮助解决问题。

**设计支持** TI 参考设计支持 可帮助您快速查找有帮助的 E2E 论坛、设计支持工具以及技术支持的联系信息。

### 12.3 商标

E2E is a trademark of Texas Instruments.

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### 12.4 静电放电警告



ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

### 12.5 术语表

**SLYZ022** — TI 术语表。

这份术语表列出并解释术语、缩写和定义。

## 13 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。



## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TCA9406DCTR</a>	Active	Production	SSOP (DCT)   8	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	NF9 (R, Z)
TCA9406DCTR.B	Active	Production	SSOP (DCT)   8	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	NF9 (R, Z)
<a href="#">TCA9406DCUR</a>	Active	Production	VSSOP (DCU)   8	3000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	(F9, NF9R) NZ
TCA9406DCUR.B	Active	Production	VSSOP (DCU)   8	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	(F9, NF9R) NZ
TCA9406DCURG4.B	Active	Production	VSSOP (DCU)   8	3000   LARGE T&R	-	Call TI	Call TI	-40 to 85	
<a href="#">TCA9406YZPR</a>	Active	Production	DSBGA (YZP)   8	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	7W
TCA9406YZPR.B	Active	Production	DSBGA (YZP)   8	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	7W

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA9406DCTR	SSOP	DCT	8	3000	180.0	13.0	3.35	4.5	1.55	4.0	12.0	Q3
TCA9406DCUR	VSSOP	DCU	8	3000	180.0	9.0	2.25	3.4	1.0	4.0	8.0	Q3
TCA9406YZPR	DSBGA	YZP	8	3000	180.0	8.4	1.11	2.1	0.56	4.0	8.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA9406DCTR	SSOP	DCT	8	3000	182.0	182.0	20.0
TCA9406DCUR	VSSOP	DCU	8	3000	182.0	182.0	20.0
TCA9406YZPR	DSBGA	YZP	8	3000	182.0	182.0	20.0



## PACKAGE OUTLINE

## VSSOP - 0.9 mm max height

## SMALL OUTLINE PACKAGE



1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-187 variation CA.

# EXAMPLE BOARD LAYOUT

DCU0008A

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 25X



4225266/A 09/2014

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DCU0008A

VSSOP - 0.9 mm max height

SMALL OUTLINE PACKAGE

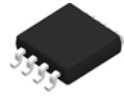


SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 25X

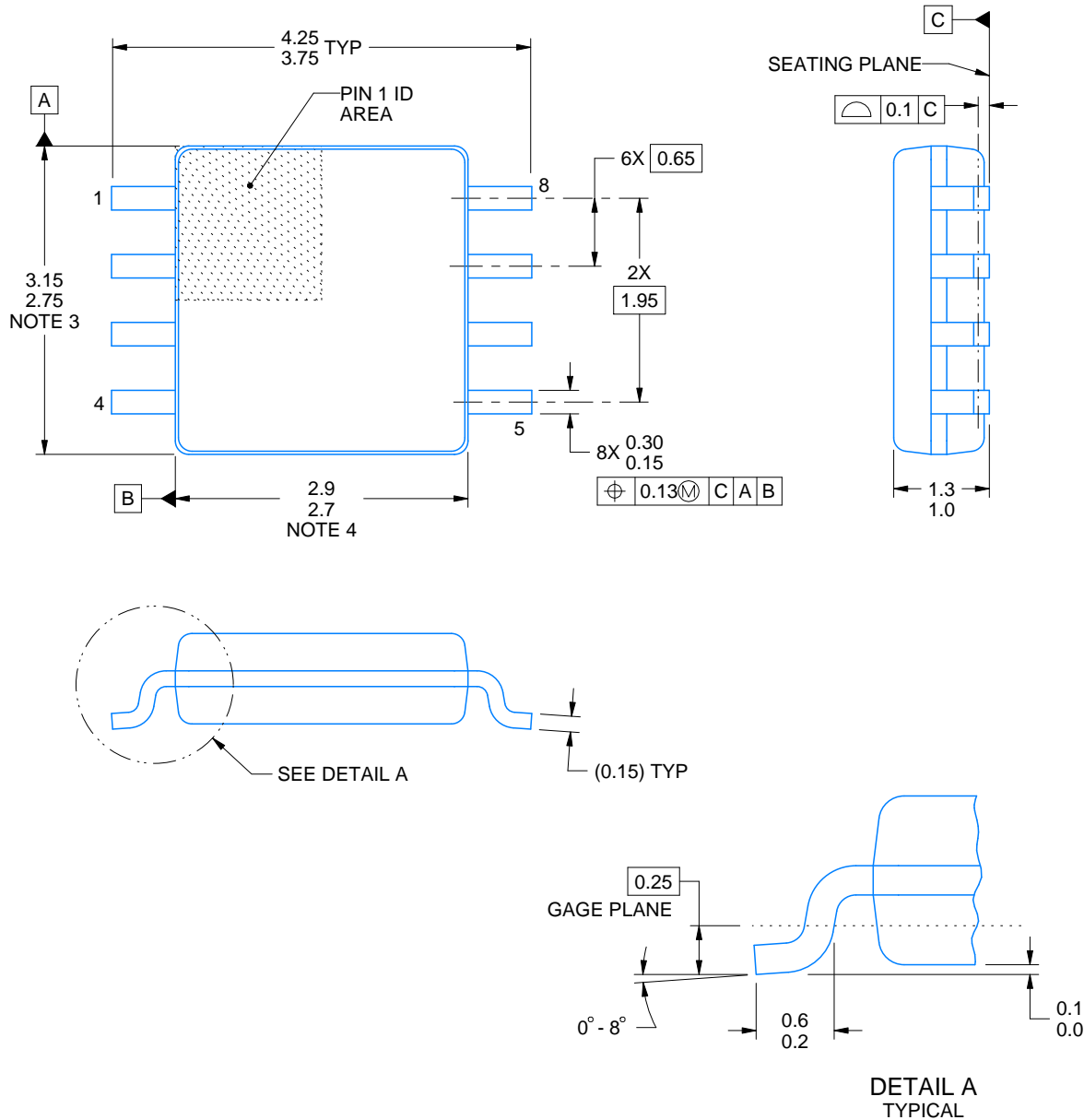
4225266/A 09/2014

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

**DCT0008A****PACKAGE OUTLINE****SSOP - 1.3 mm max height**

SMALL OUTLINE PACKAGE



4220784/C 06/2021

**NOTES:**

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.

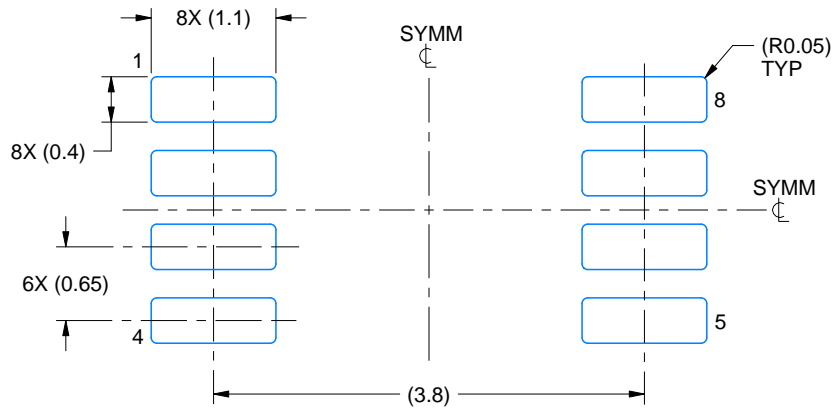


# EXAMPLE BOARD LAYOUT

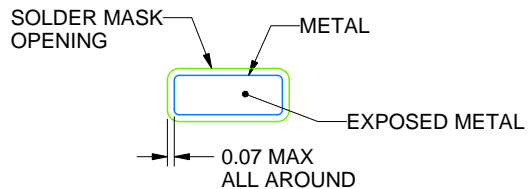
DCT0008A

SSOP - 1.3 mm max height

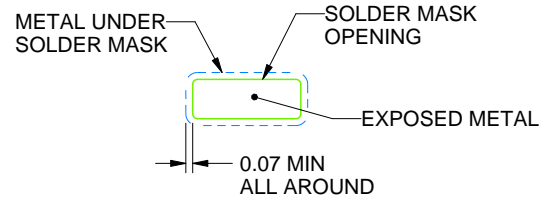
SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



NON SOLDER MASK  
DEFINED



SOLDER MASK  
DEFINED

SOLDER MASK DETAILS

4220784/C 06/2021

NOTES: (continued)

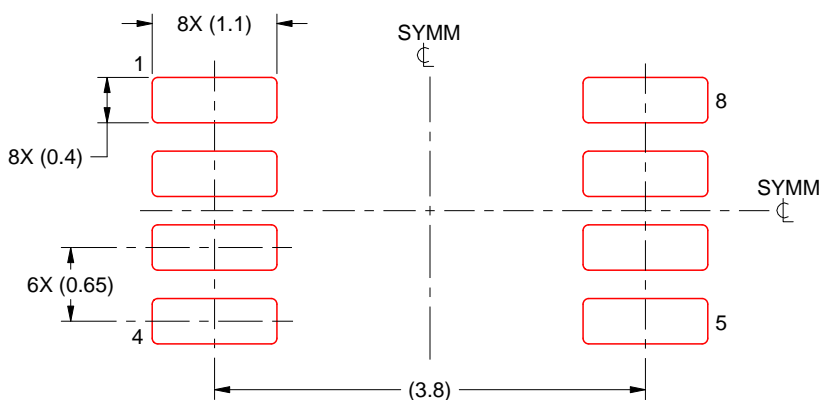
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DCT0008A

SSOP - 1.3 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4220784/C 06/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

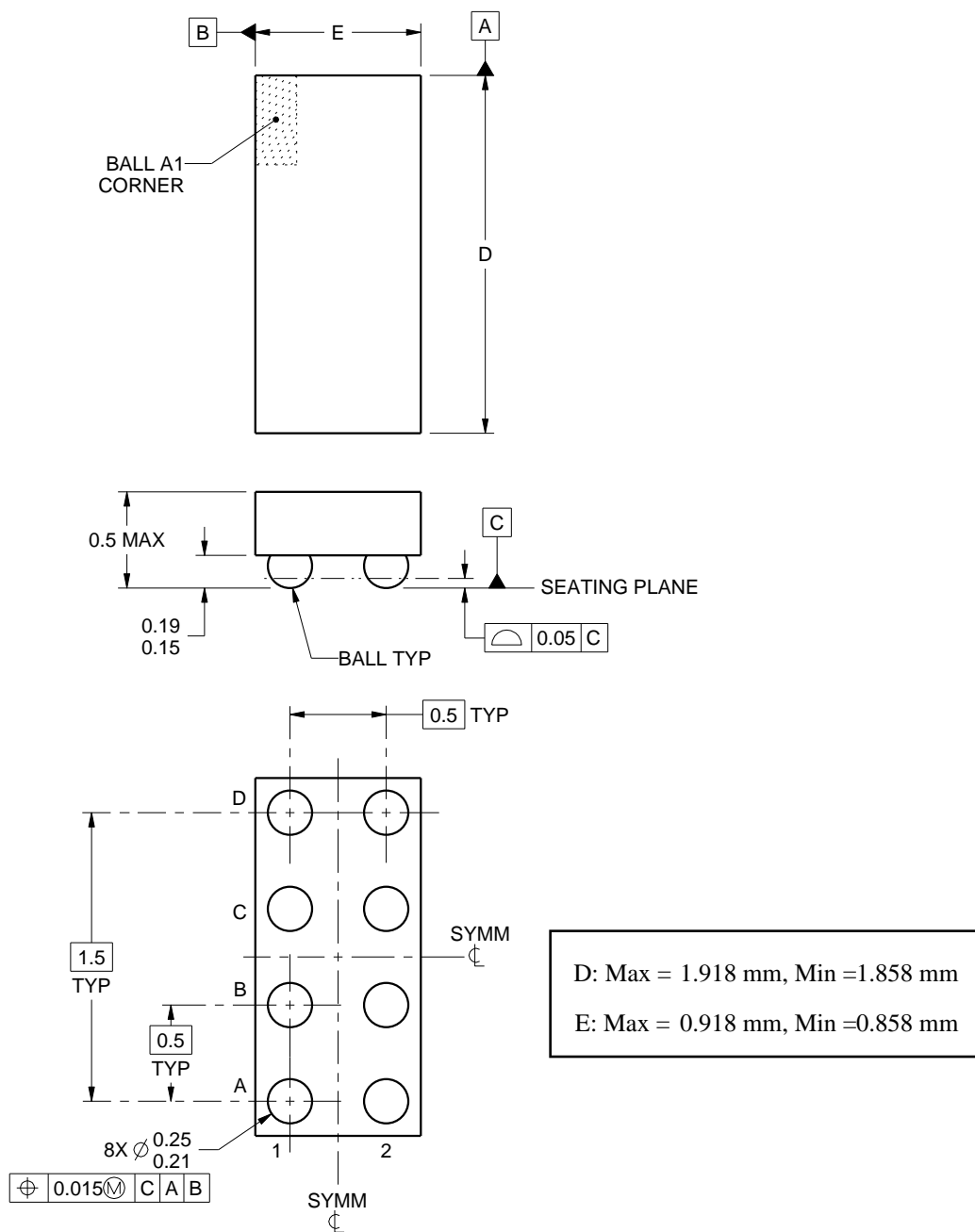
YZP0008



# PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



4223082/A 07/2016

## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

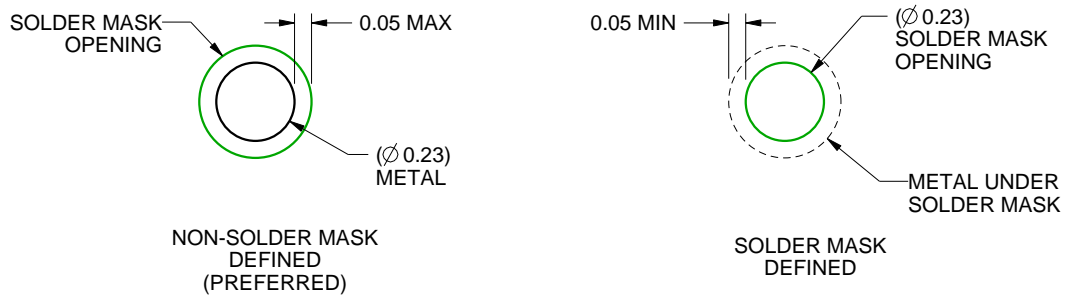
YZP0008

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:40X



SOLDER MASK DETAILS  
NOT TO SCALE

4223082/A 07/2016

NOTES: (continued)

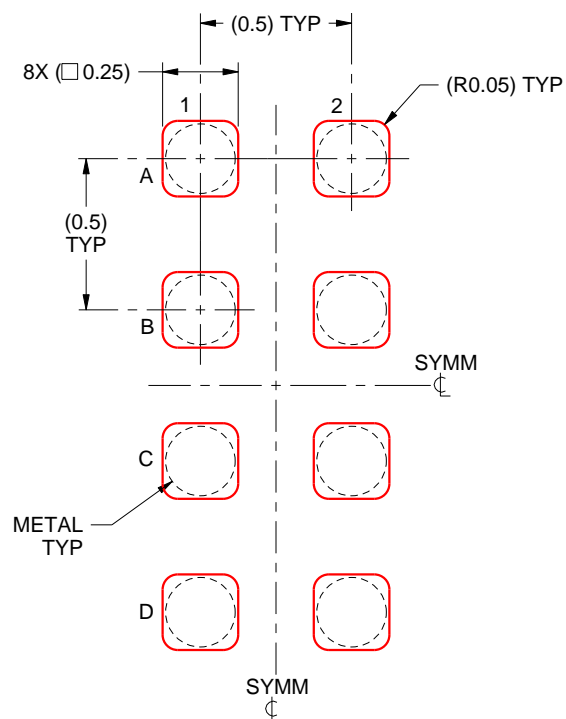
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 ([www.ti.com/lit/snva009](http://www.ti.com/lit/snva009)).

## EXAMPLE STENCIL DESIGN

YZP0008

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:40X

4223082/A 07/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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